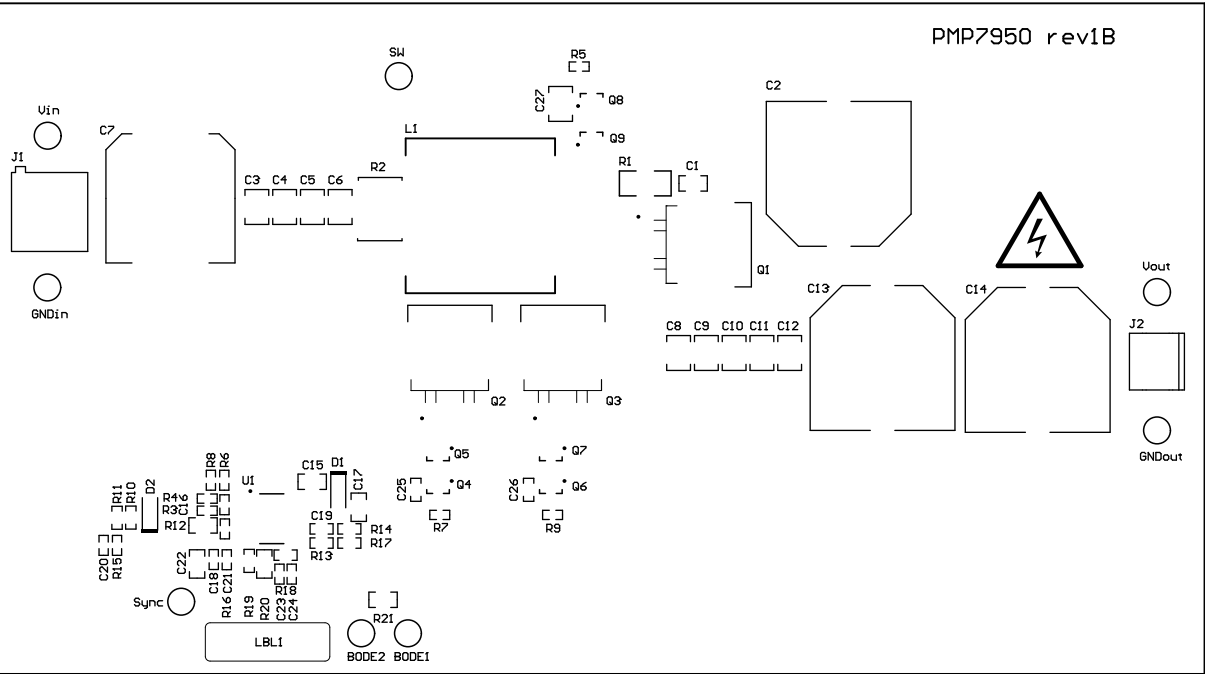
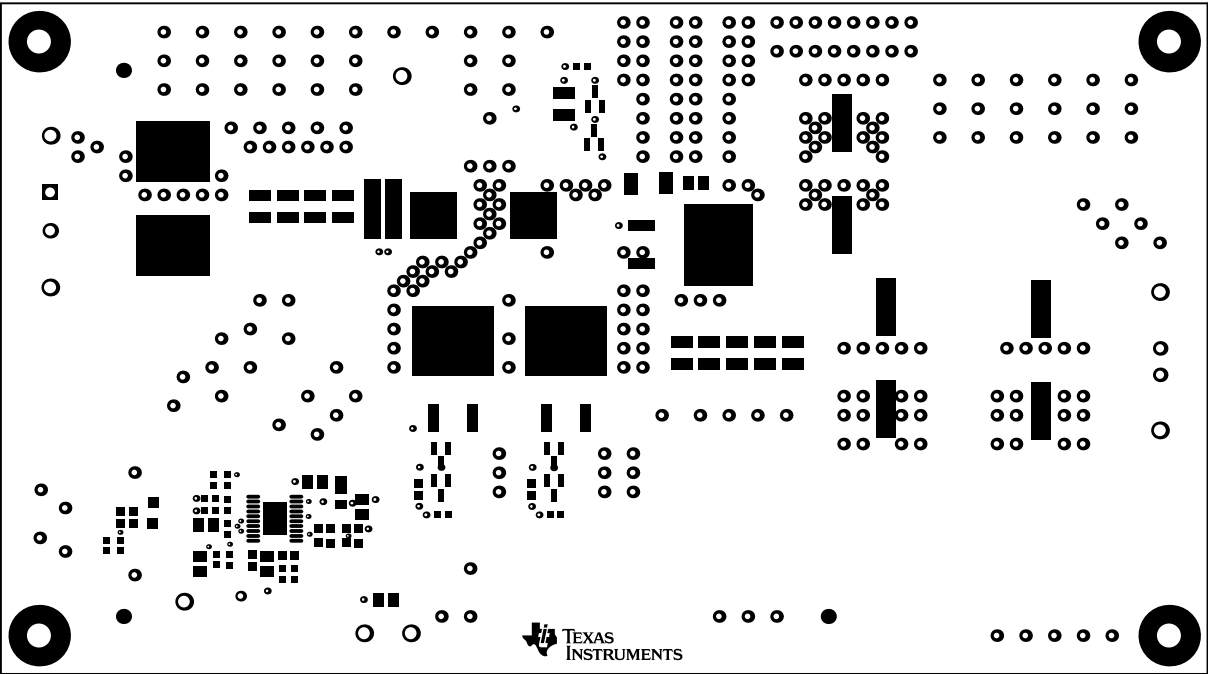


This document can handle board shapes up to 7.9in x 10in, although our panel vendors top out at 7in x 10in.
To re-size the board shape, do the following:
Select lines on M1 Board Outline and delete (easy in single layer mode...shift+s)
Draw a rectangle using lines (example will be for a 4 x 6 board
Enter Place Line mode (keyboard pl)
keyboard jo to jump to origin, hit enter
keyboard jl to jump to location, set x to 6000, hit enter twice
keyboard jl to jump to location, set x to 6000 and y to 4000, hit enter twice
keyboard jl to jump to location, set x to 0 and y to 4000, hit enter twice
keyboard jo to jump to origin, hit enter
Hit ESC twice to exit place line mode
Select lines on M1 Board Outline
Menu Design\Board Shape\Define from Selected Objects (keyboard dsd)
To define a Keep-Out that mirrors the board outline:
Menu Design\Board Shape\Create Primitives From Board Shape (keyboard dsp)
Set the Keep-Out Layer as the layer, set width as preferred
Ensure Route Tool Outline is selected, hit enter

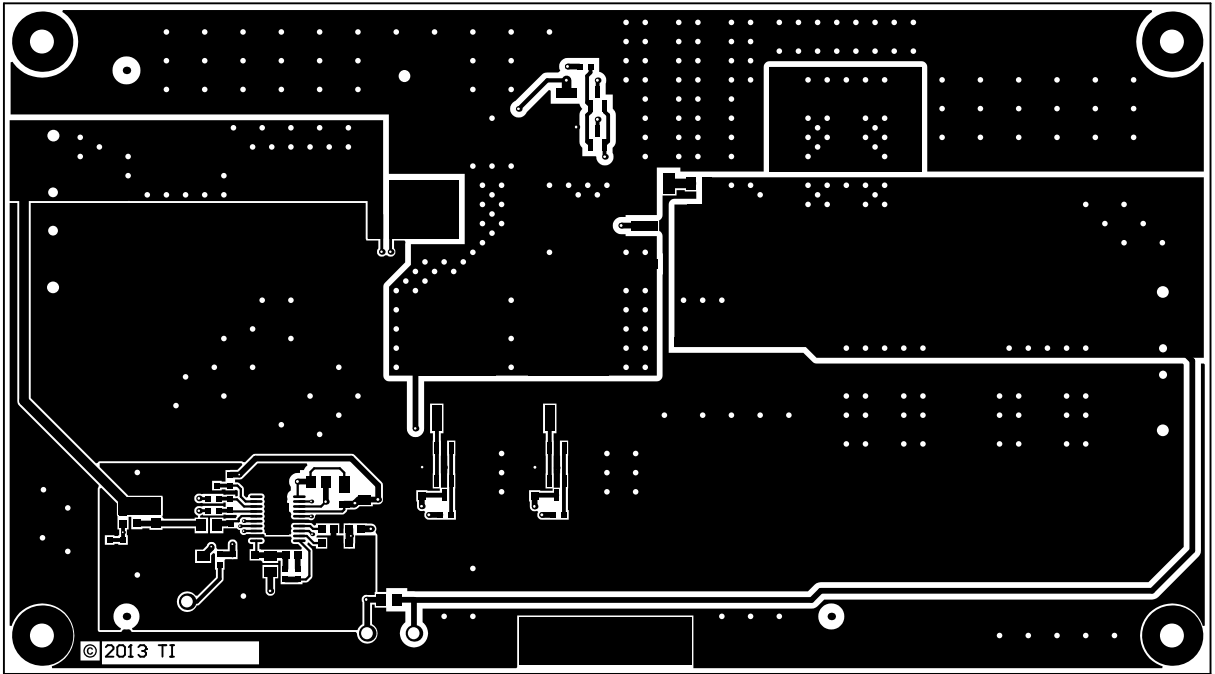
If you re-size the board, don't forget to move the drill table strings on the Drill Drawing Layer...they should be just to the right of your board shape



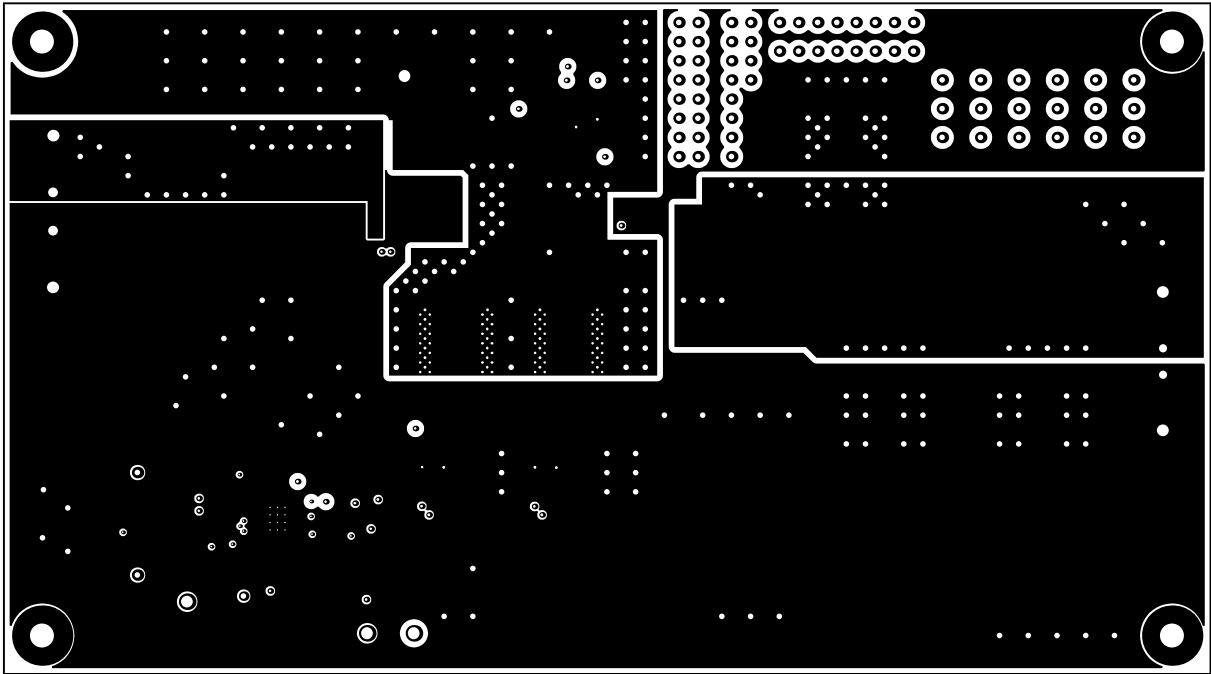
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev1B REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay		
PLOT NAME = Top Overlay	GENERATED : 6/9/2015 2:54:35 PM	TEXAS INSTRUMENTS



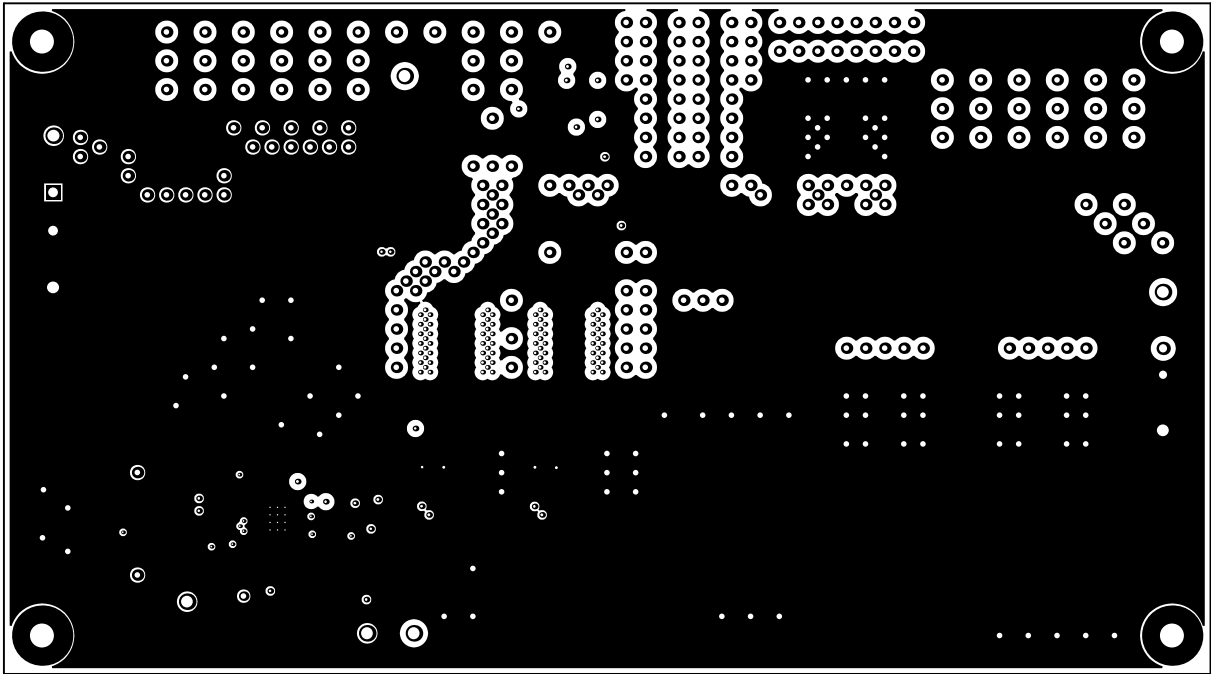
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/9/2015	2:54:35 PM	TEXAS INSTRUMENTS



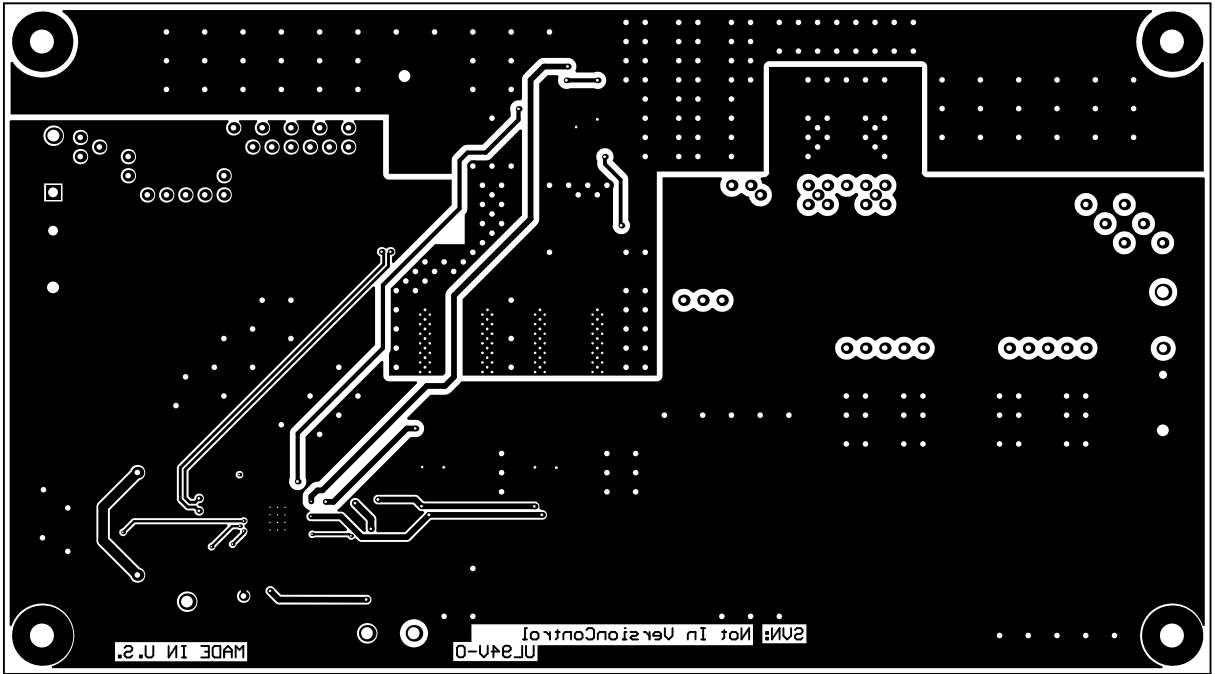
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/9/2015	2:54:36 PM	TEXAS INSTRUMENTS



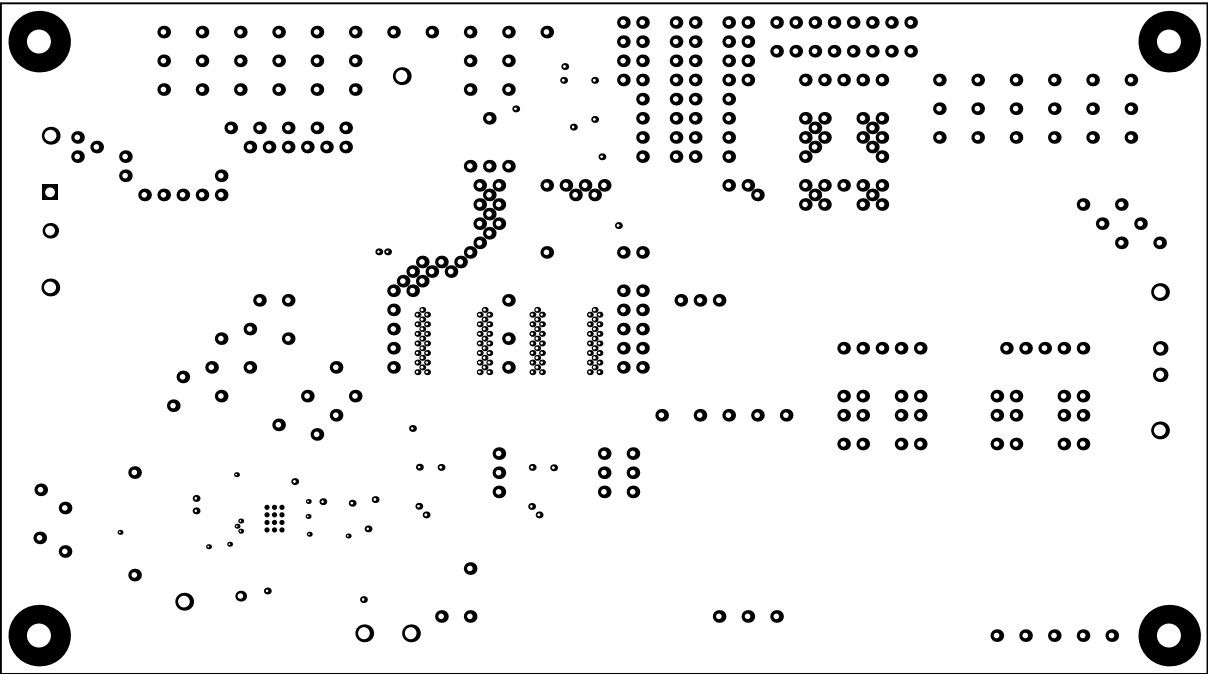
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 1	GENERATED : 6/9/2015	2:54:36 PM	TEXAS INSTRUMENTS



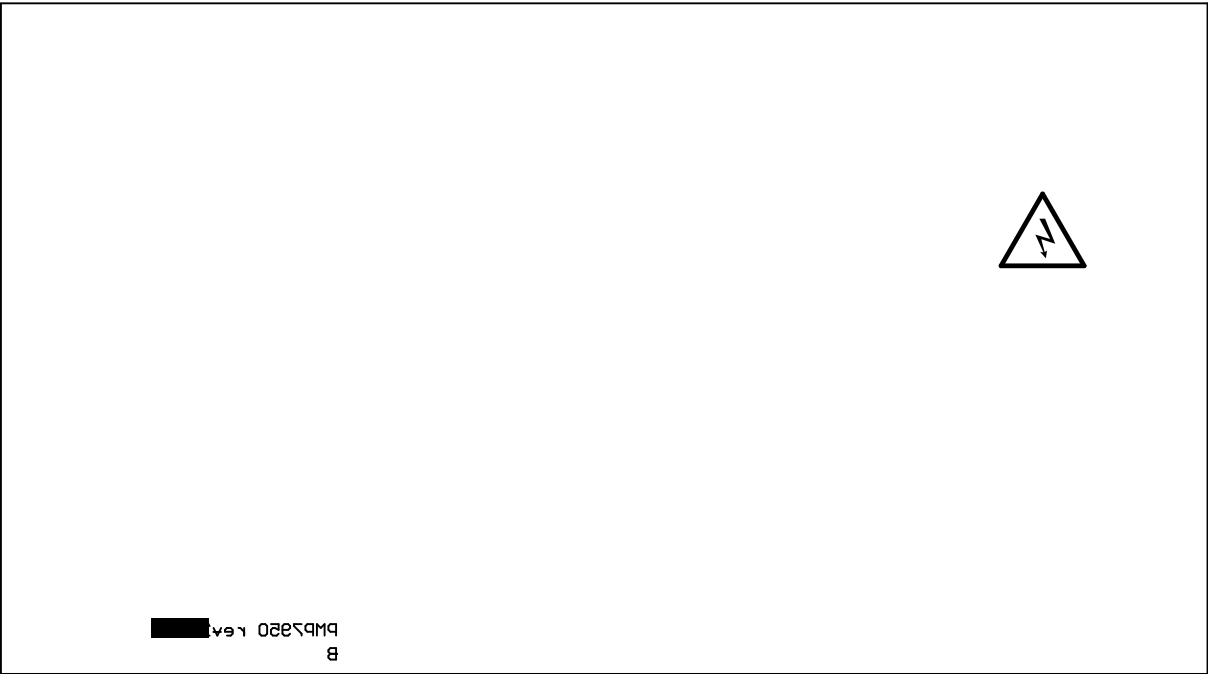
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 2	GENERATED : 6/9/2015	2:54:37 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	B REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED	: 6/9/2015 2:54:38 PM	TEXAS INSTRUMENTS



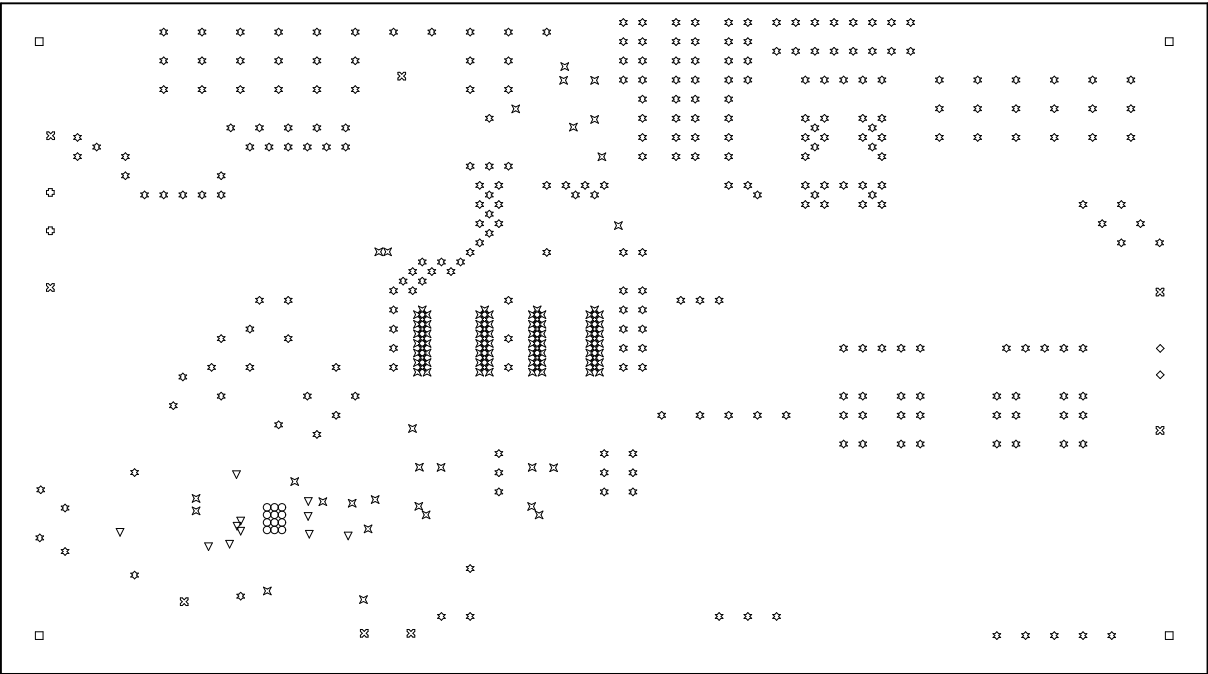
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/9/2015	2:54:38 PM	TEXAS INSTRUMENTS



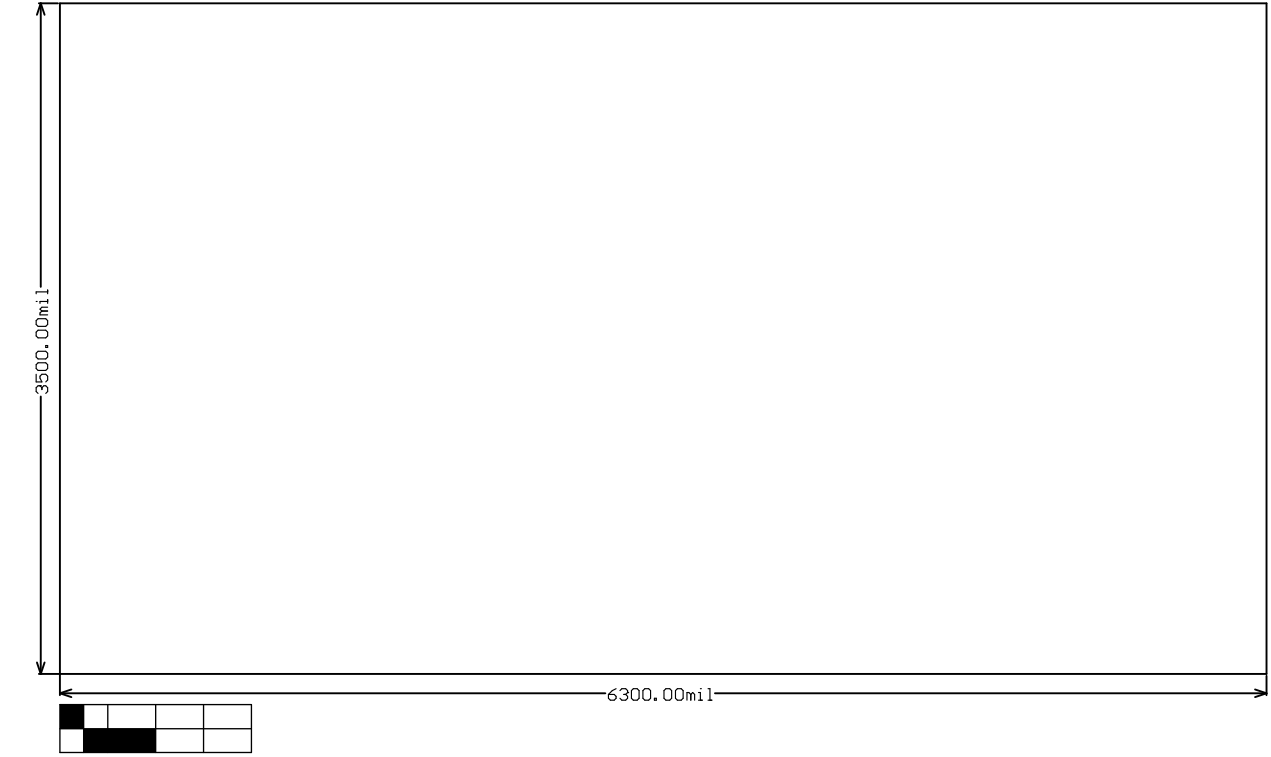
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 6/9/2015	2:54:39 PM	TEXAS INSTRUMENTS

Symbol	Hit Count	Tool Size	Plated	Hole Type
○	12	8mil (0.203mm)	PTH	Round
▽	11	10mil (0.254mm)	PTH	Round
⌘	112	15mil (0.381mm)	PTH	Round
☆	298	30mil (0.762mm)	PTH	Round
◇	2	43.307mil (1.1mm)	PTH	Round
⊗	2	51.181mil (1.3mm)	PTH	Round
⊗	8	63mil (1.6mm)	PTH	Round
□	4	125.984mil (3.2mm)	PTH	Round
449 Total				

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/9/2015	2:54:39 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev	IB REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/9/2015 2:54:40 PM	TEXAS INSTRUMENTS	

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